

I CLAIM:

100-271-3501650

1. An improved structure of a chip package for used in the package structure of a digital photographic lens device with hidden chip connected with transmission lines, characterized in that the improved structure comprises a sectional of flexible circuit board and a hard thin board and the mounting legs of the photographic lens device assembly are mounted onto the flexible photographic lens device assembly having corresponding electrically connection points, and the flexible circuit board is connected to the back panel of the digital photographic lens device and is mounted with the hard thin plate.
5. 2. The improved structure of a chip package as set forth in claim 1, wherein the flexible circuit board is an electrically conductive connection points being printed on one section of the continuation strap body.
10. 3. The improved structure of a chip package as set forth in claim 1 or 2, wherein the section of the flexible circuit board, extended out from one end of the digital photographic lens device assembly is formed with a reserved folded length and the surface of the plate is provided with flexible conductive connection circuit of related circuit.